FIG.1

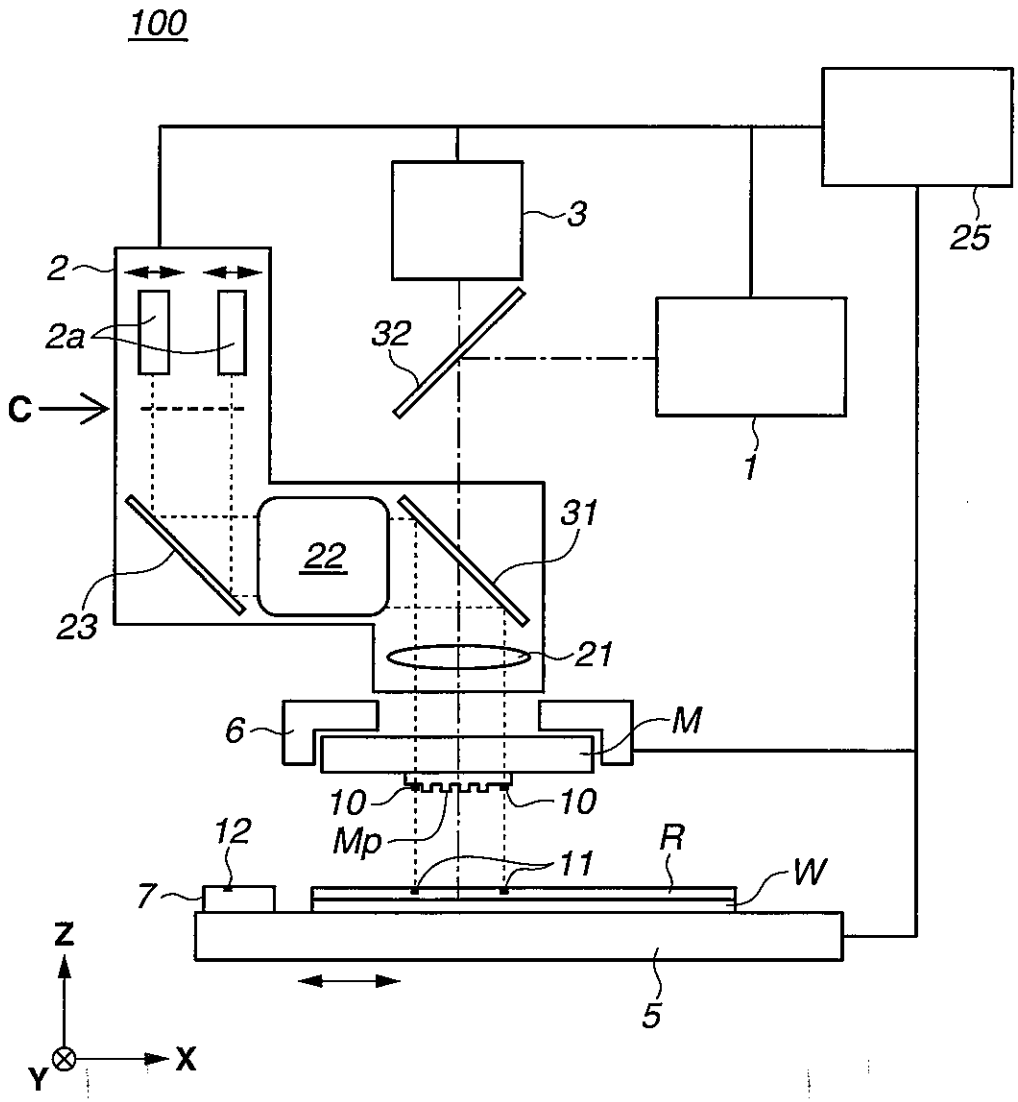


FIG.2

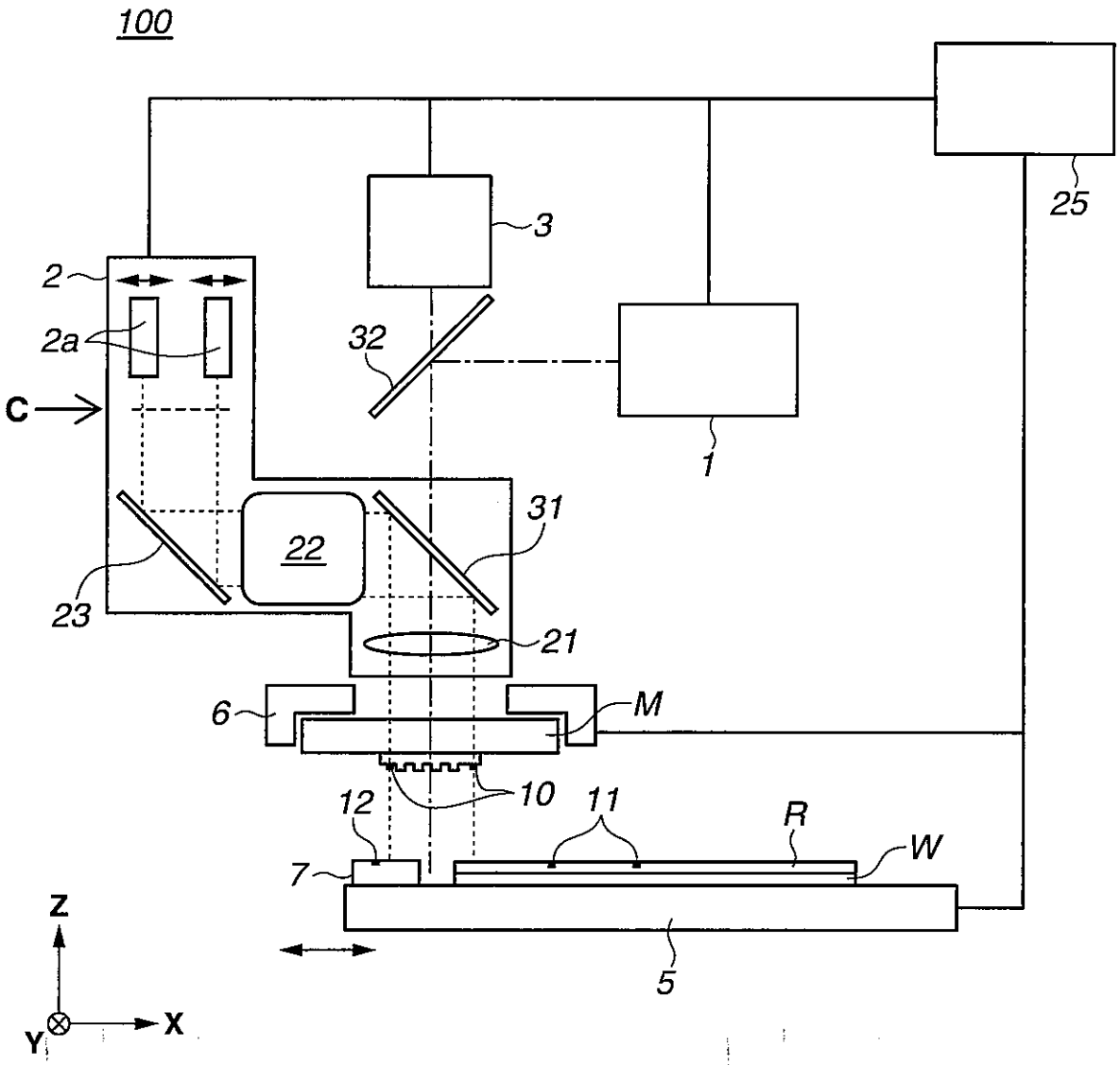


FIG.3

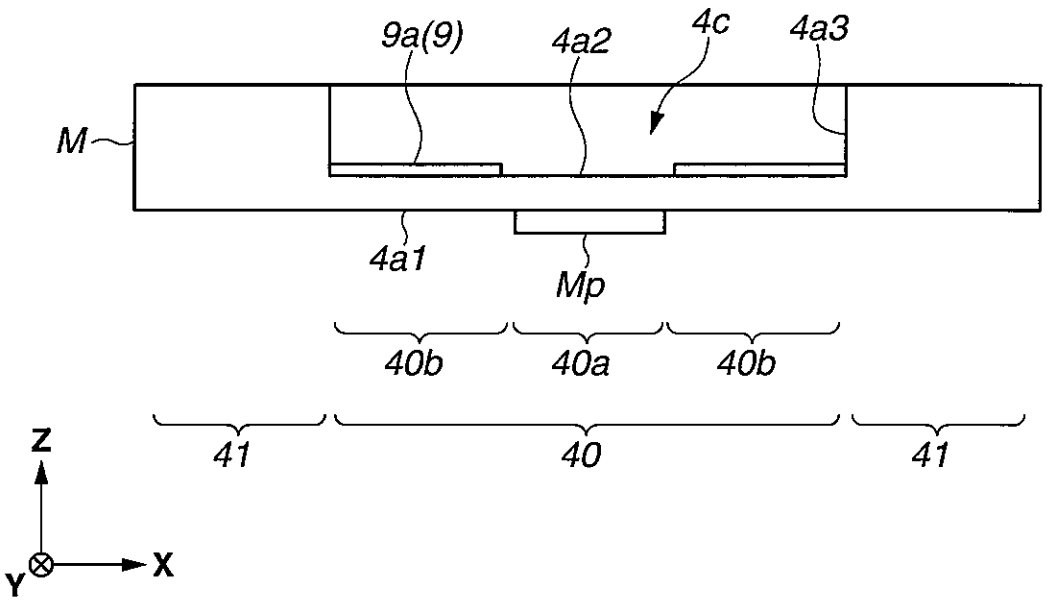


FIG.4

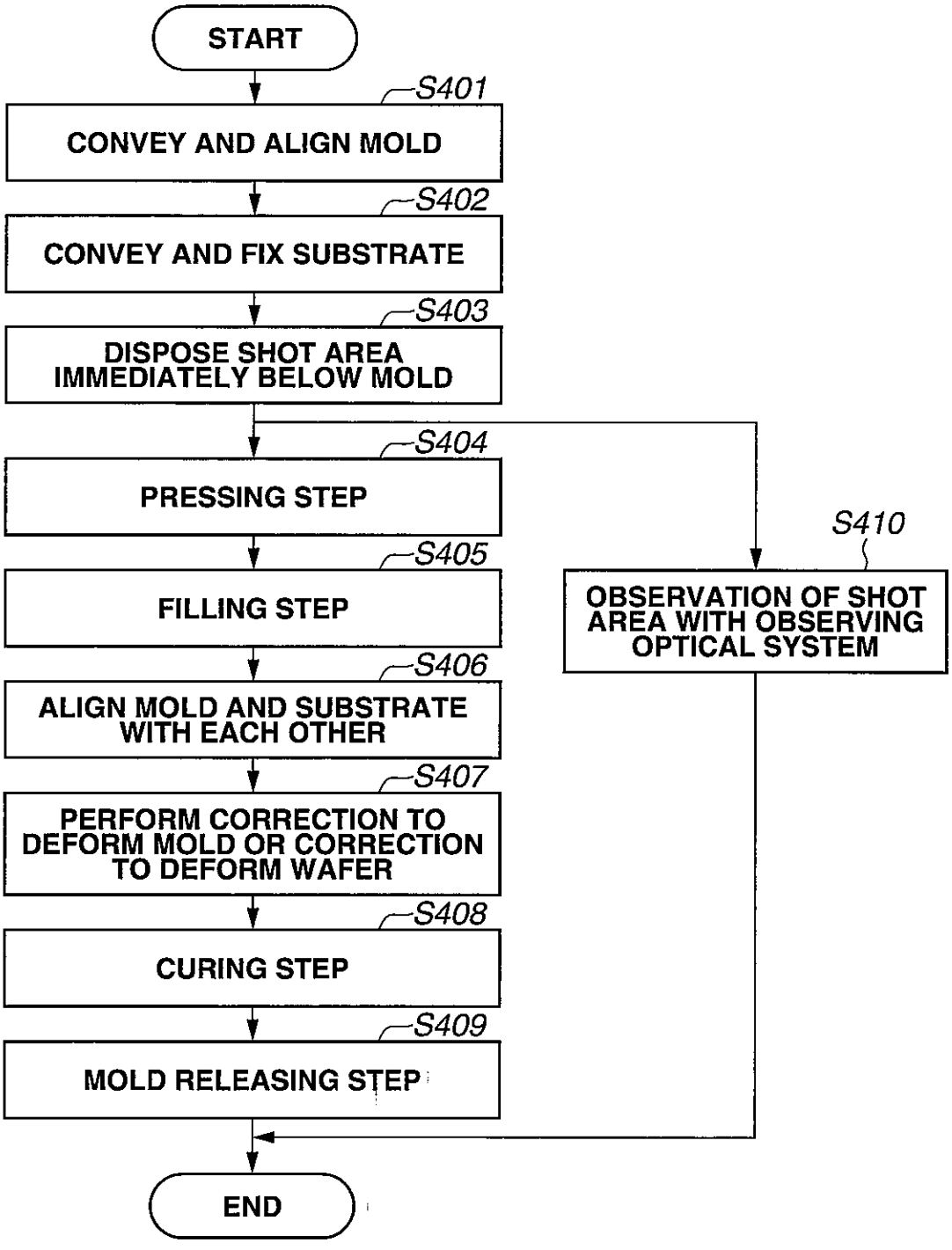

START
S401
CONVEY AND ALIGN MOLD
S402
CONVEY AND FIX SUBSTRATE
S403
DISPOSE SHOT AREA IMMEDIATELY BELOW MOLD
S404
PRESSING STEP
S405
FILLING STEP
S406
ALIGN MOLD AND SUBSTRATE WITH EACH OTHER
S407
PERFORM CORRECTION TO DEFORM MOLD OR CORRECTION TO DEFORM WAFER
S408
CURING STEP
S409
MOLD RELEASING STEP
S410
OBSERVATION OF SHOT AREA WITH OBSERVING OPTICAL SYSTEM
END

FIG.5A

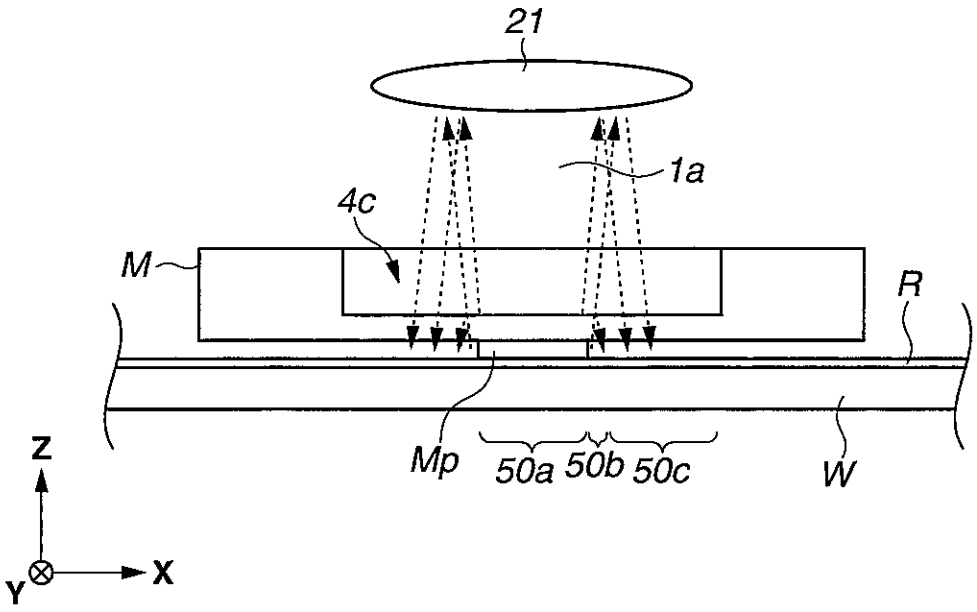


FIG.5B

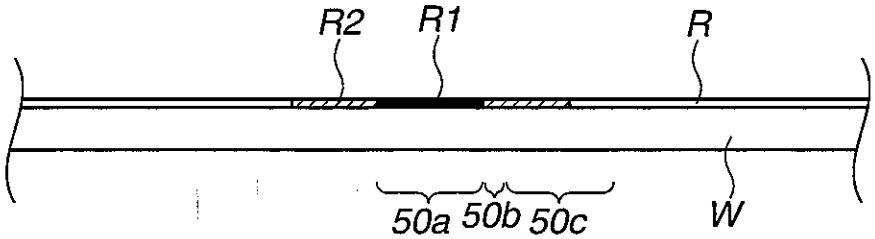


FIG.6

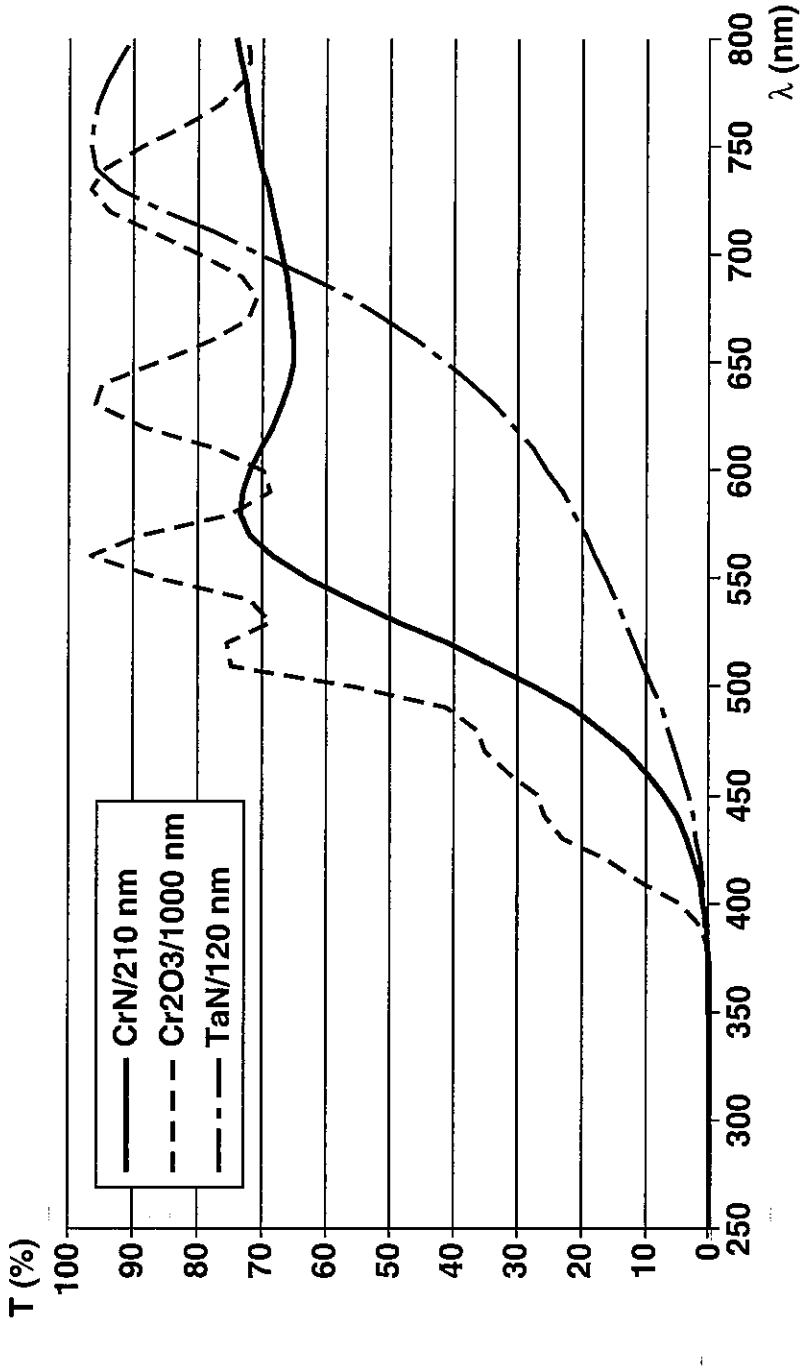

T (%)
100
90
80
70
60
50
40
30
20
10
0
250
300
350
400
450
500
550
600
650
700
750
800
λ (nm)
CrN/210 nm
Cr2O3/1000 nm
TaN/120 nm

FIG.7A

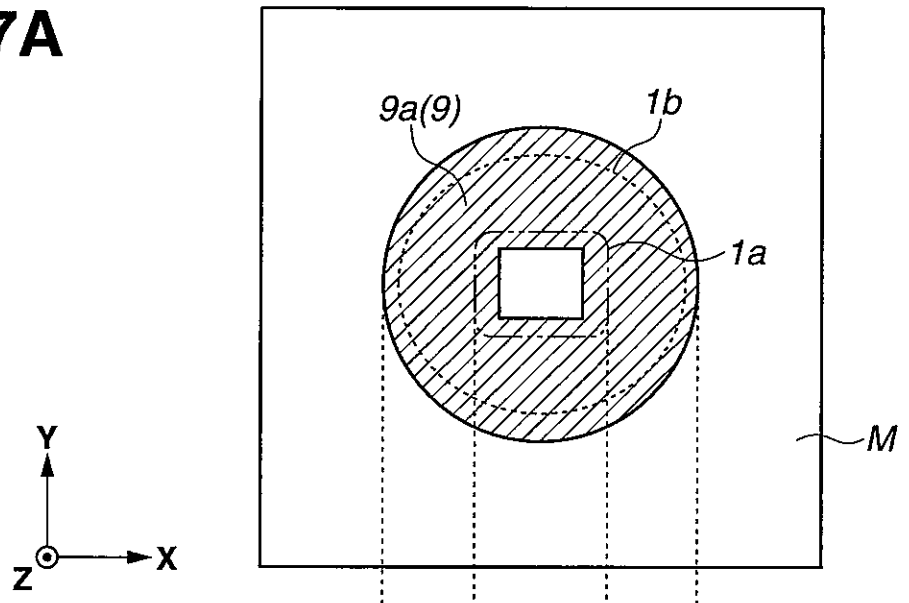


FIG.7B

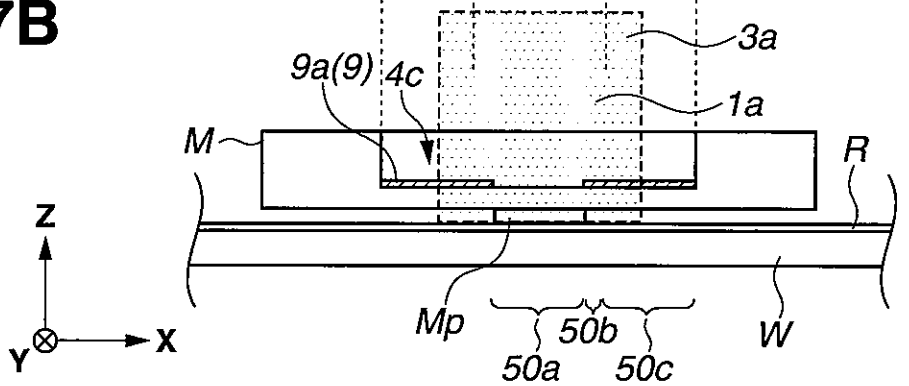


FIG.7C

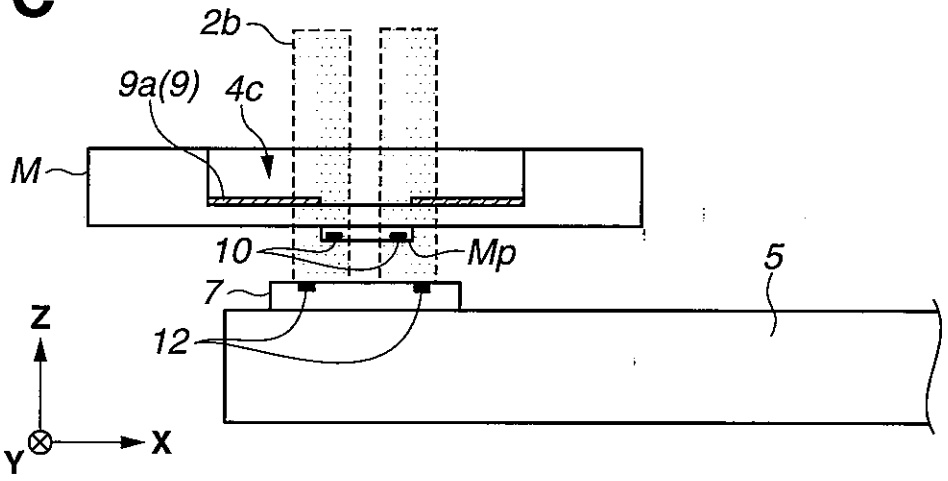


FIG.8A

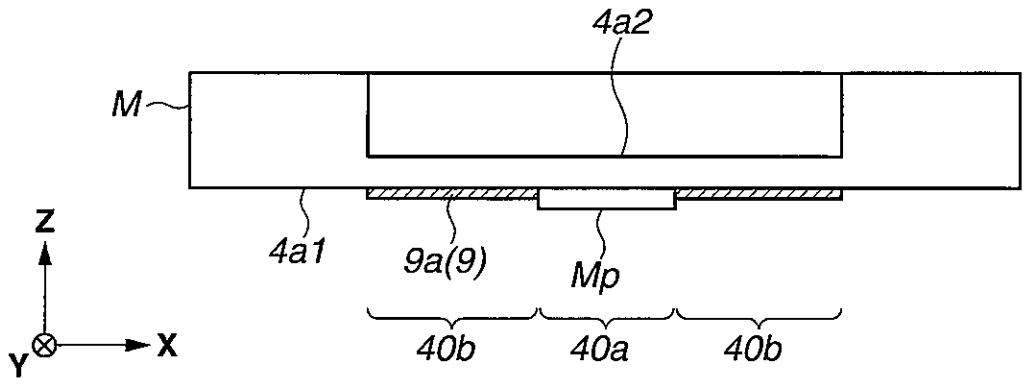


FIG.8B

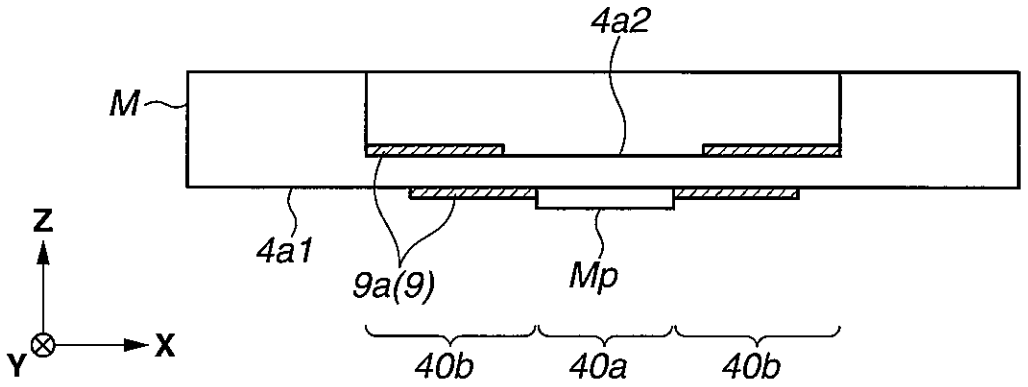


FIG.9A

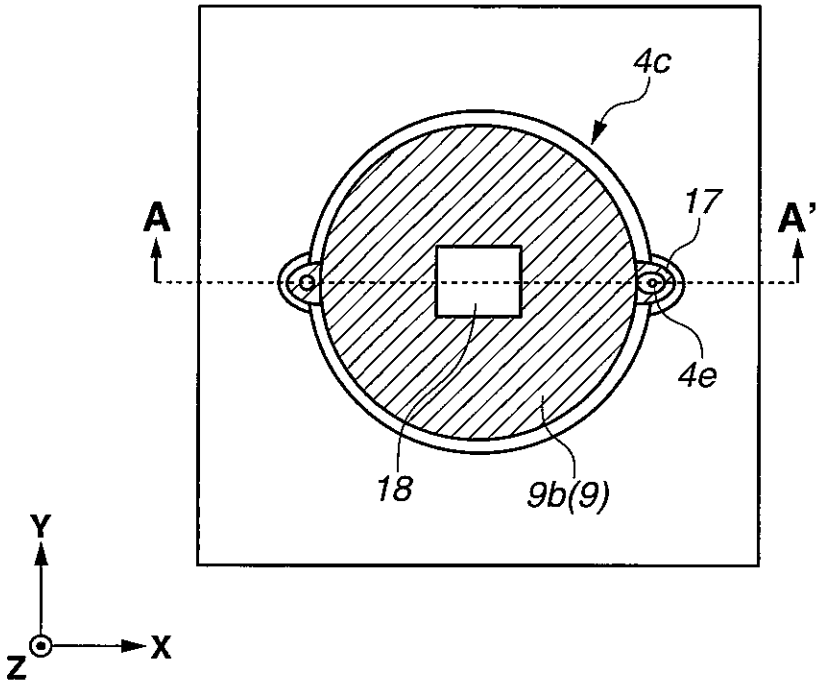


FIG.9B

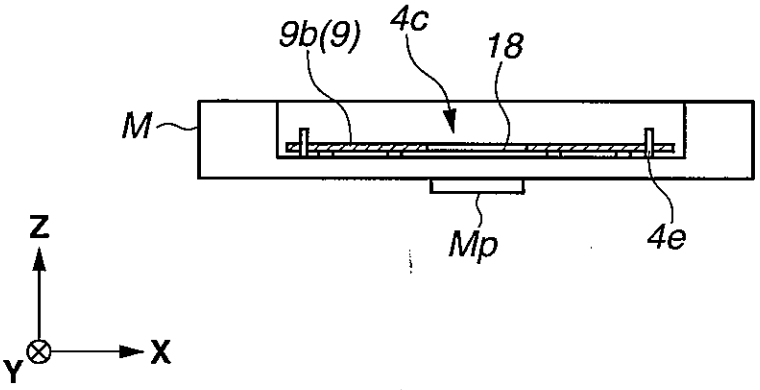


FIG.10

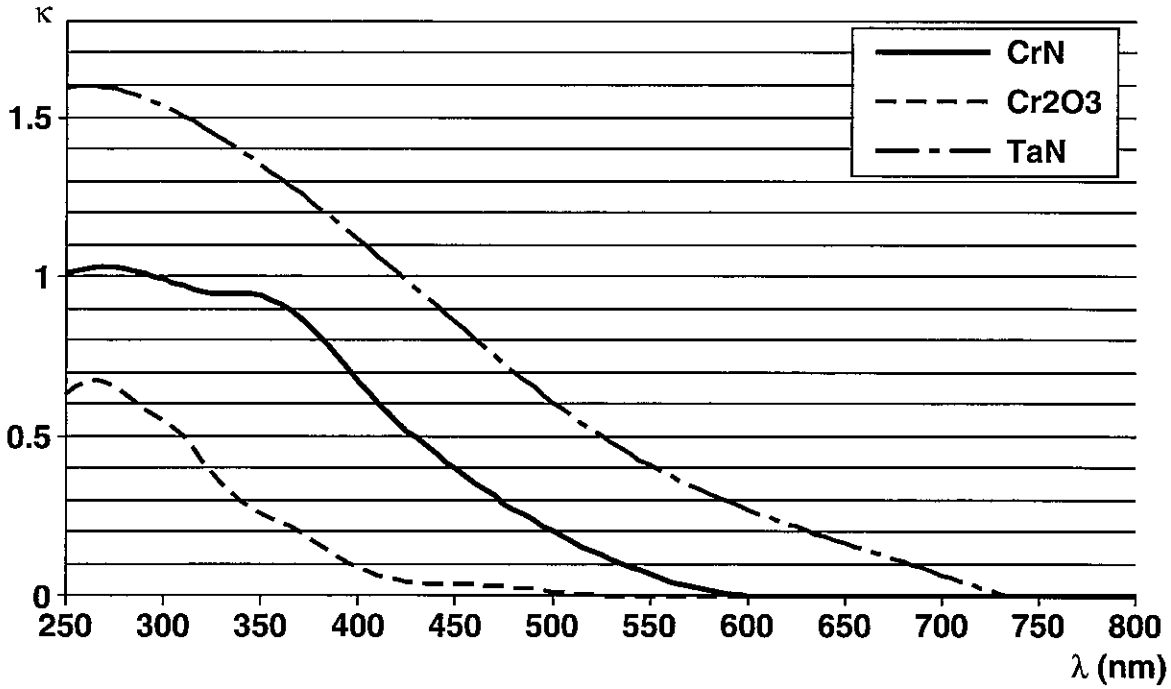

κ
1.5
1
0.5
0
250
300
350
400
450
500
550
600
650
700
750
800
λ (nm)
CrN
Cr2O3
TaN

FIG.11A

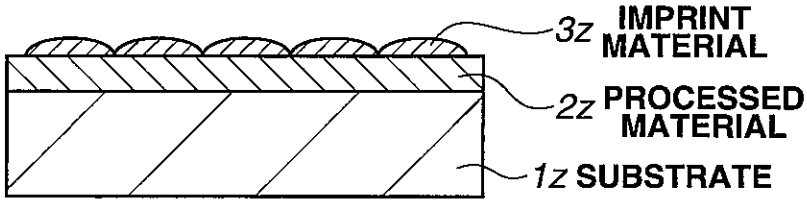


FIG.11B

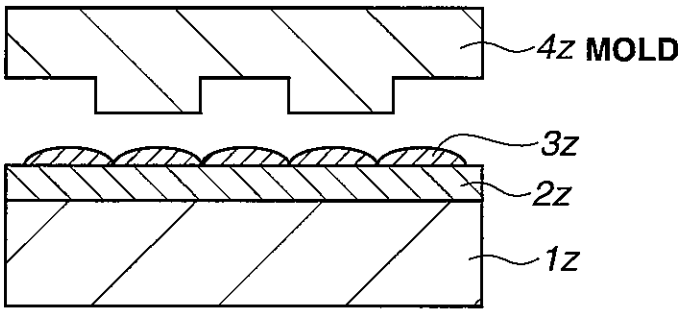


FIG.11C

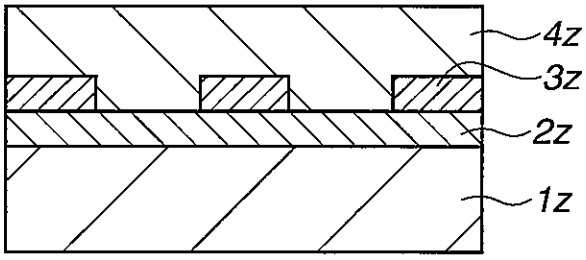


FIG.11D

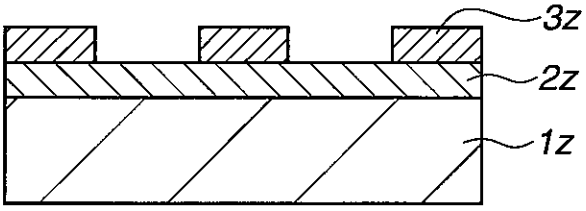


FIG.11E

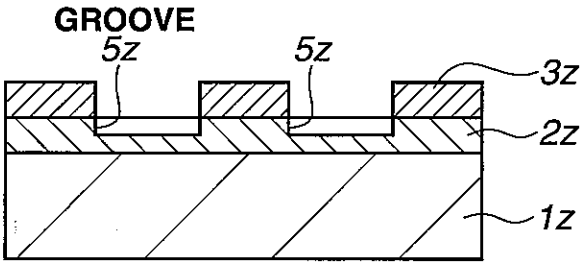


FIG.11F

